

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Application of: )  
Chen, et al. ) Confirmation No.: 9818  
Serial No.: 10/810,965 ) Examiner: Trinh, Hoa B.  
Filed: March 26, 2004 ) Group Art Unit: 2814  
For: Novel Method to Improve Bump Reliability for ) TKHR Docket: 252016-2530  
Flip Chip Device ) Top-Team: 0503-A30731US

**RESPONSE TO FINAL OFFICE ACTION**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

The FINAL Office Action mailed April 24, 2005 has been carefully considered. In response thereto, please consider the following remarks.